

QA Test Report

PCA-6751

(Thermal Profile Test)

Report No:00H002A1

Issue Stamp

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Department

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Approval

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Test Engineer

QA Lab Reliability test

Test Date: May 16, 2000 ~ May 17, 2000

Test Site: Advantech QA Environment Lab

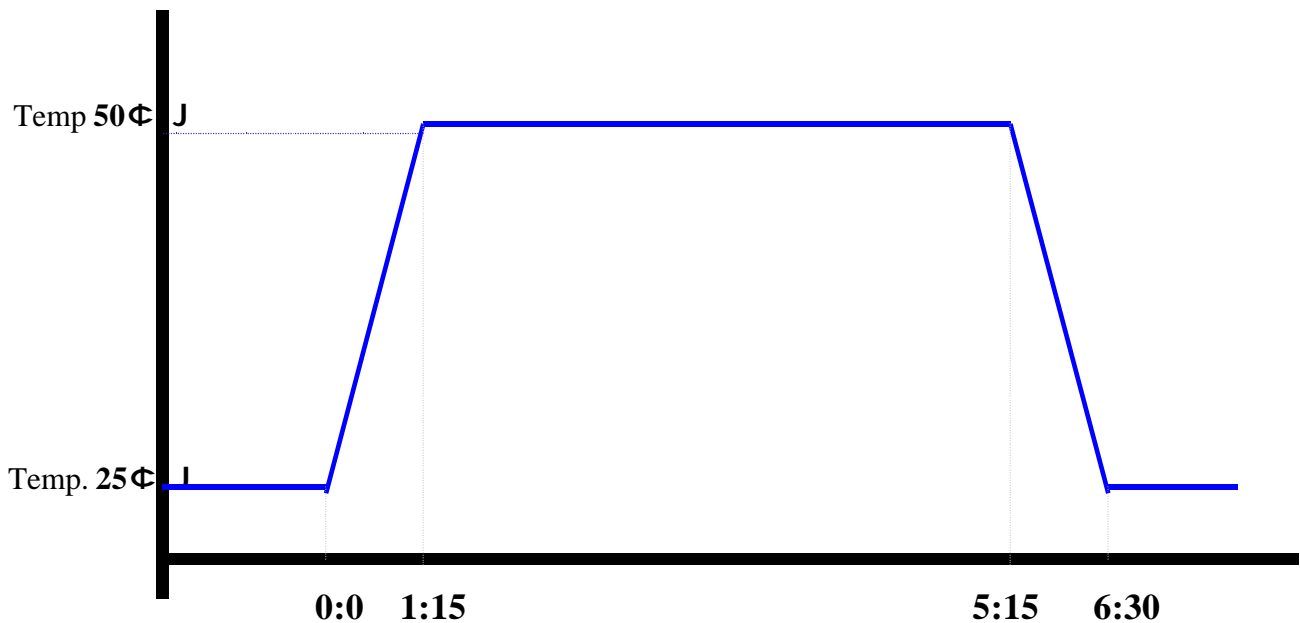
Performed By: Art Liao

Purpose: The Component change verify test

Test Standard: Reference IEC68-2-2 Testing procedures
Test Bb: Dry heat test

Test Condition:

1. Test Temperature: 50°C J
2. Temp dwell time: 4hrs or more
3. Test Software: Win 98 VCD player
4. Test Environment Curve:



QA Lab Reliability test

Test Equipment: 1. Programmable Temperature & Humidity Chamber

KSON Instrument Tech CO.,LTD.

Model:THS-D4L+-150-LN2

S/N:1519

Date of calibration:07-9-1999

2. DATA LOGGER

OMEGA CO. LTD.

Model : OM-5100

S/N : 9412-0404

Date of Calibration : 09-20-1999

Sample Configuration & Quantion Under Test:

Using two PCA-6751 Slot PCs with the following options installed

Ver. A1 01-2

1. CPU : Intel Pentium 266MHz
2. Core Logic : Intel FW82439TX
Intel FW82371EB
3. EDORAM: HY57V651620aTC-10 32MB
4. SRAM : LP61G6464AF-5
5. VGA : CHIPS 69000
6. LAN : Intel SB82558B
7. Clock : PLL52C66-01CXC
8. I/O : W83977TF-A
9. Heat Sink Pad: metal

Ver. B1

1. CPU : Intel Pentium 266MHz
2. Core Logic : Intel FW82439TX
Intel FW82371EB
3. EDORAM: HY57V651620aTC-10 32MB
4. SRAM : LP61G6464AF-5
5. VGA : CHIPS 69000
6. LAN : RTL 8139B
7. Clock : PLL52C66-01CXC
8. I/O : W83977TF-A
9. Heat Sink Pad: Plumbago

QA Lab Reliability test

Electronic function check:

Electronic function check:

1. All system function must have properly test program to test and passed this test.
2. Running OS for Win 98 the system cannot have degradation of the performance.

Test Data:

Num	Item	SPEC	A1	B1	Remark
1	Ambient temp.	50	50	50	
2	CPU surface temp.	95	71.6	73.1	-1.5
3	CPU Heat Sink surface temp.	95	71.0	69.8	1.2
4	Core Logic FW82439TX surface temp.	90	78.0	76.2	
5	VGA CHIPS 69000 surface temp.	90	75.3	71.5	
6	Clock surface temp.	90	73.6	78.5	
7	Core Logic FW82371EB surface temp.	90	65.0	62.0	
8	Q1 CS5205-1 surface temp.	120	59.8	71.8	
9	D2 831B10 surface temp.	12	68.5	67.4	

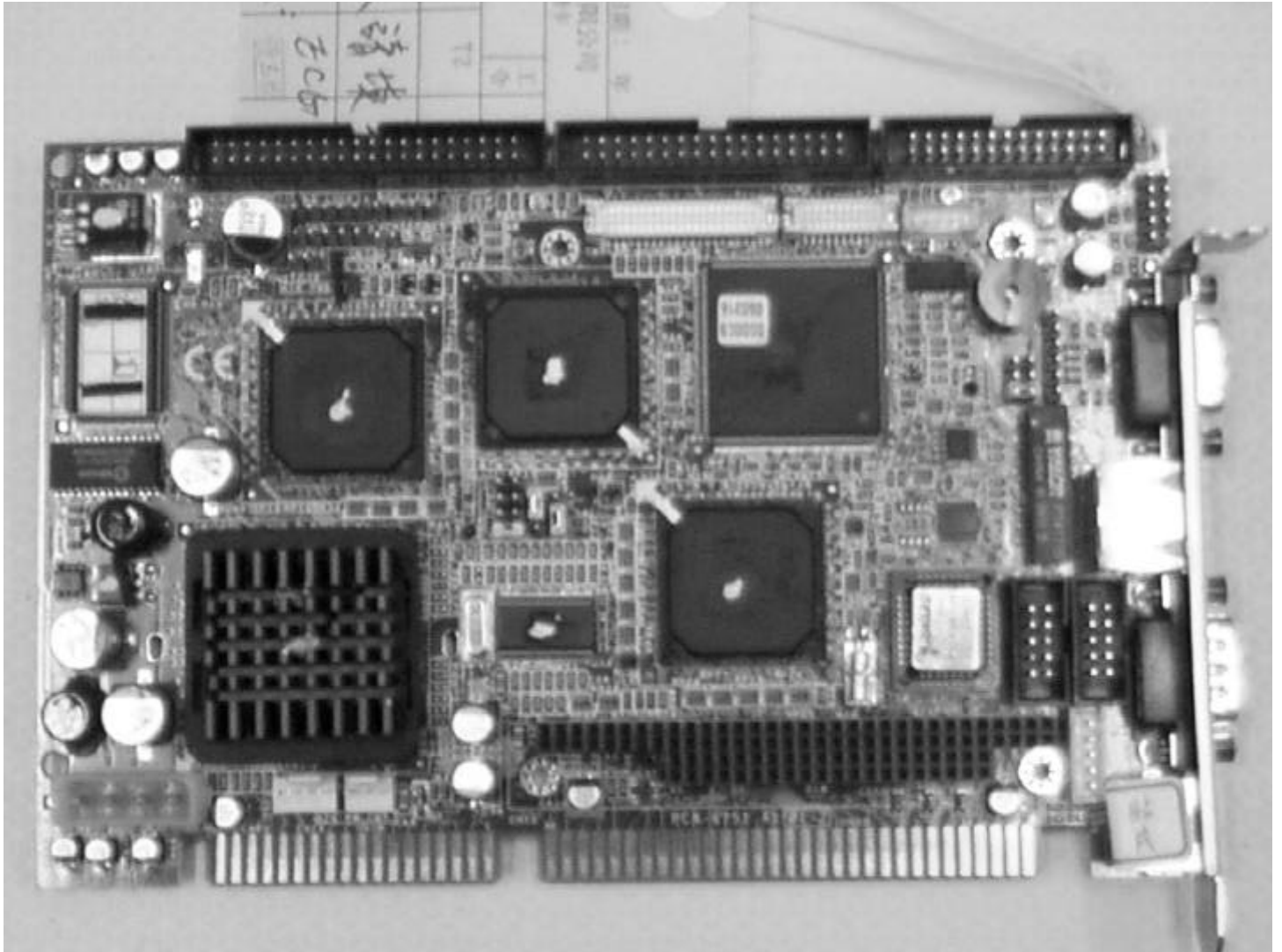
Test Result :

1. Test is no electronic function degradation has found, and without any incurably physical damage degradation the performance.
2. The CPU temperature with thermal Pad use metal better plumbago.

Conclusion:

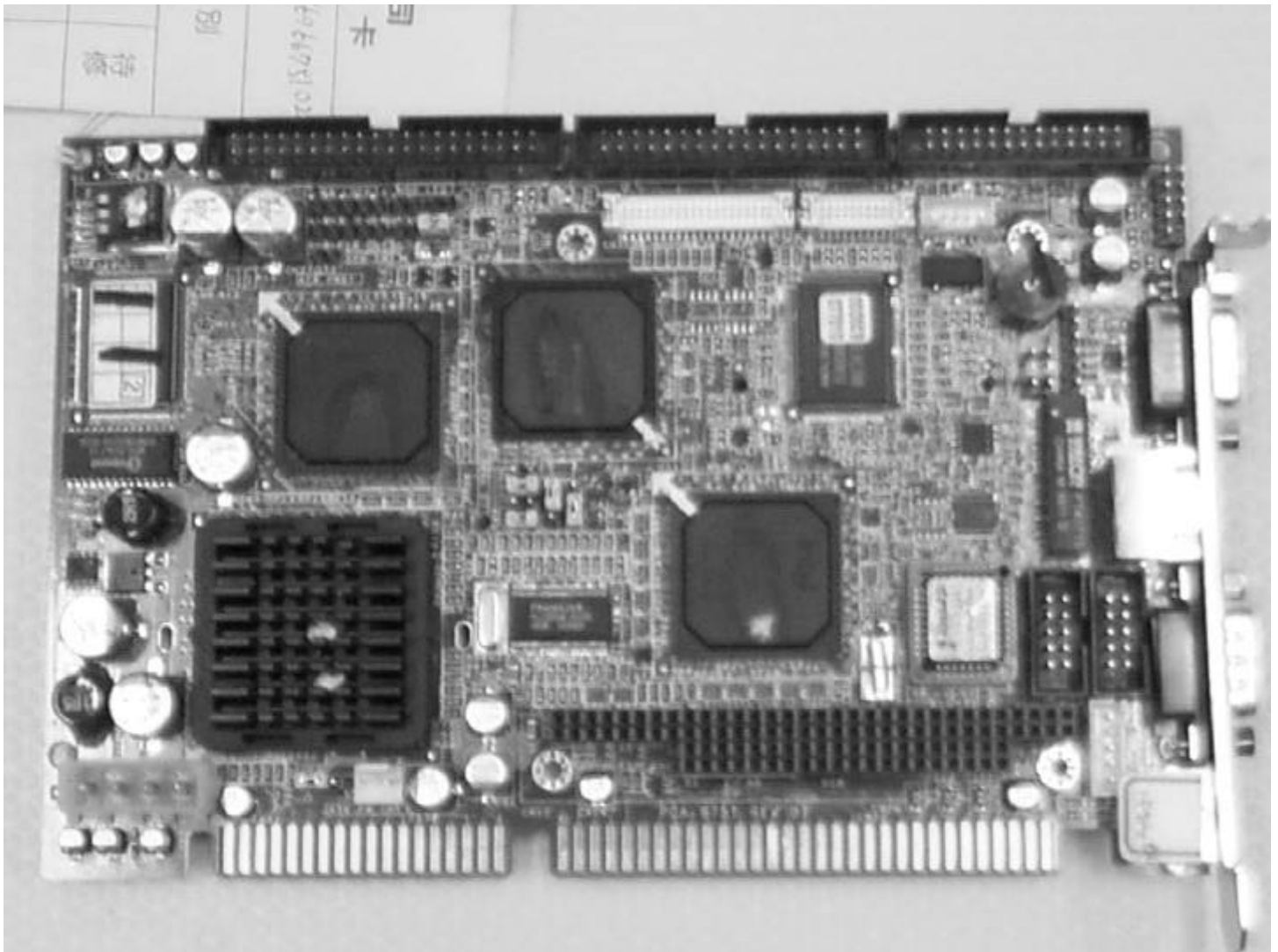
The metal thermal pad better plumbago pads.

Photograph :



PCA-6751 Ver. A1 01-2 Slot PCs

Photograph :



PCA-6751 Ver. B1 Slot PCs